IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of

Atty. Docket

JOHANNES F.A. REINIERS

NL 000445

Serial No.

Group Art Unit

Filed:

CONCURRENTLY

Ex.

Title:

SYSTEM COMPRISING AT LEAST TWO PRINTED CIRCUIT BOARDS

Commissioner for Patents Washington, D.C. 20231

PRELIMINARY AMENDMENT

Sir:

Prior to calculation of the filing fee and examination, please amend the above-identified application as follows:

IN THE CLAIMS

Please amend the claims as follows:

- 3. (amended) A system as claimed in claim 1, wherein the inner surface of the recesses is coated on all sides with an electroconductive material, in particular a metal.
- 4. (amended) A system as claimed in claim 2, wherein the electroconductive material is provided by means of electrolysis.
- 5. (amended) A system as claimed in claim 2, wherein the thickness of the electroconductive material ranges between 25 μm and 40 μm , and is in particular approximately 35 μm .

- 6. (amended) A system as claimed in claim 1, wherein the electroconductive pins have a diameter below 3 mm, in particular below 2 mm, and more in particular below 1.5 mm.
- 7. (amended) A method of manufacturing printed circuit boards which are part of a system as claimed in claim 1, wherein the electroconductive pins are formed by material removal, in particular milling or drilling, from one printed circuit board.

REMARKS

The foregoing Preliminary Amendment to the claims were made solely to avoid filing the claims in the multiple dependant form so as to avoid the additional filing fee.

The claims were not amended in order to address issues of patentability and Applicant respectfully reserves all rights he may have under the Doctrine of Equivalents. Applicant furthermore reserves his right to reintroduce subject matter deleted herein at a later time during the prosecution of this application or continuing applications.

Respectfully symmitted

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APPENDIX

Amended Claims

- 3. (amended) A system as claimed in claim 1 or 2, wherein the inner surface of the recesses is coated on all sides with an electroconductive material, in particular a metal.
- 4. (amended) A system as claimed in claim 2—or 3, wherein the electroconductive material is provided by means of electrolysis.
- 5. (amended) A system as claimed in claim 2, 3 or 4, wherein the thickness of the electroconductive material ranges between 25 μ m and 40 μ m, and is in particular approximately 35 μ m.
- 6. (amended) A system as claimed in any one of the preceding claims 1 through 5claim 1, wherein the electroconductive pins have a diameter below 3 mm, in particular below 2 mm, and more in particular below 1.5 mm.
- 7. (amended) A method of manufacturing printed circuit boards which are part of a system as claimed in any one of the preceding claims 1 through 6claim 1, wherein the electroconductive pins are formed by material removal, in particular milling or drilling, from one printed circuit board.